

ABSTRACT OF THE DISCLOSURE

An image sensor package includes plural lower metal sheets, plural upper metal sheets stacked on the lower metal sheets, and an encapsulant for encapsulating the lower and upper metal sheets. The lower metal formed with a first hole, the upper metal sheets formed a second hole penetrated from the upper surface to the lower surface. Wherein the encapsulant filled into the second hole and first hole to tighten the upper metal sheets and the lower metal sheets. A photosensitive chip arranged within the chamber, plural wires for electrically connecting the chip to the upper surfaces of the lower metal sheets, and a transparent layer arranged on the frame layer to cover the chip.